

MM

**B -14 EP**  
**CASE 948AW**  
**ISSUE C**

SAE 1:1

DATE 09 OCT 2012

NOTES:

1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
2. CONTROLLING DIMENSION: MILLIMETERS.
3. DIMENSION b DOES NOT INCLUDE DAMBAR PROTRUSION. ALLOWABLE PROTRUSION SHALL BE 0.07 mm MAX. AT MAXIMUM MATERIAL CONDITION. DAMBAR CANNOT BE LOCATED ON THE LOWER RADII OF THE FOOT. MINIMUM SPACE BETWEEN PROTRUSION AND ADJACENT LEAD IS 0.07.
4. DIMENSION D DOES NOT INCLUDE MOLD FLASH, PROTRUSIONS OR GATE BURRS. MOLD FLASH, PROTRUSIONS OR GATE BURRS SHALL NOT EXCEED 0.15 mm PER SIDE. DIMENSION D IS DETERMINED AT DATUM H.
5. DIMENSION E1 DOES NOT INCLUDE INTERLEAD FLASH OR PROTRUSIONS. INTERLEAD FLASH OR PROTRUSIONS SHALL NOT EXCEED 0.25 mm PER SIDE. DIMENSION E1 IS DETERMINED AT DATUM H.
6. DATUMS A AND B ARE DETERMINED AT DATUM H.
7. A1 IS DEFINED AS THE VERTICAL DISTANCE FROM THE SEATING PLANE TO THE LOWEST POINT ON THE PACKAGE BODY.
8. SECTION B IS TO BE DETERMINED AT 0.10 TO 0.25 mm FROM THE LEAD TIP.

| DM | MES  |      |
|----|------|------|
|    | M    | MAX  |
| A  | iii  | 1.20 |
| A1 | 0.05 | 0.15 |

|   |      |      |
|---|------|------|
| b | 0.19 | 0.30 |
|---|------|------|

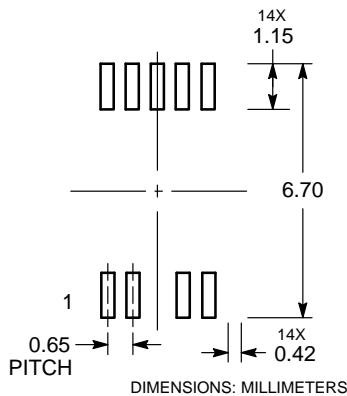
|   |      |      |
|---|------|------|
| c | 0.09 | 0.20 |
|---|------|------|

|   |      |      |
|---|------|------|
| L | 0.45 | 0.75 |
|---|------|------|

|   |    |    |
|---|----|----|
| M | 0° | 8° |
|---|----|----|

**GENR**  
**MS DAGRM**

**DES FB**



- XXXX = Specific Device Code
- A = Assembly Location
- L = Wafer Lot
- Y = Year
- W = Work Week
- = Pb iFree Package

\*For additional information on our Pb iFree strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

\*This information is generic. Please refer to device data sheet for actual part marking. Pb iFree indicator, "G" or microdot "▪", may or may not be present.